

Customer No.: 31561
Application No.: 10/709,588
Docket No.: 10790-US-PA

REMARKS

Response to 35 U.S.C. 121

In response to the Restriction Requirement mailed on February 28, 2006, a complete listing of all of the claims is presented herewith. Applicant would like to elect Group I, claims 1-9, drawn to a method of making a flip chip package, classified in class 438, subclass 108. Please cancel Group II, claims 10-21, drawn to a flip chip package, classified in class 257, subclass 778 without waiver, prejudice or disclaimer:

If the Examiner believes that a telephone conference would expedite the examination of the above-identified patent application, the Examiner is invited to call the undersigned.

Date : *March 24, 2006*

Respectfully submitted,

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